



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.013mm	3.5	
4	TOP Layer	Copper	0.017mm		
5	Dielectric1	FR-4	0.076mm	4.8	
6	GROUND1	Copper	0.035mm		
7	Dielectric5	FR-4	0.152mm	4.8	
8	Mid Layer1	Copper	0.035mm		
9	Dielectric2	FR-4	0.173mm	4.8	
10	POWER1	Copper	0.035mm		
11	Dielectric6	FR-4	0.152mm	4.8	
12	Mid Layer2	Copper	0.035mm		
13	Dielectric3	FR-4	0.152mm	4.8	
14	GROUND2	Copper	0.035mm		
15	Dielectric7	FR-4	0.152mm	4.8	
16	POWER2	Copper	0.035mm		
17	Dielectric8	FR-4	0.173mm	4.8	
18	Mid Layer3	Copper	0.035mm		
19	Dielectric4	FR-4	0.152mm	4.8	
20	GROUND3	Copper	0.035mm		
21	Dielectric9	FR-4	0.076mm	4.8	
22	BOTTOM Layer	Copper	0.017mm		
23	Bottom Solder	Solder Resist	0.013mm	3.5	
24	Bottom Overlay				
25	Bottom Paste				

IMPORTANT: This layer stack was designed to achieve:
 40ohm (+/- 10%) characteristic impedance with 0.15mm trace width;
 50ohm (+/- 10%) with 0.095mm trace width(inner layers) and 0.1mm trace width(outer layers).
 Please adjust this stack as appropriate to achieve this goal!